



Materials Declaration

Package	CSP BGA
Body Size	9 X 9
Ball Count	100
Option	Pb-Free
Ball Size	0.45

Molding Compound			
Item	% of Compound	Weight (g)	PPM
Silica	85	6.09 E-02	25182
Phenol Resin	6.5	4.65 E-03	1926
Epoxy Resin	6.5	4.65 E-03	1926
Carbon Black	0.5	3.58 E-04	148
Metal Hydroxide	1	7.16 E-04	296
Sub-Total		7.12 E-02	29477

Laminate			
Item	% of Laminate	Weight (g)	PPM
BT-Epoxy	28	1.64 E-02	6797
Glass Fiber	25	1.47 E-02	6069
Copper	19	1.11 E-02	4612
Gold	11	6.45 E-03	2670
Nickel	7.8	4.58 E-03	1893
Solder Mask	9.35	5.49 E-03	2270
Sub-Total		5.88 E-02	24311

Solder Ball			
Item	% of Solder Balls	Weight (g)	PPM
Sn	96.5	2.10 E+00	867611
Ag	3	6.52 E-02	26972
Cu	0.5	1.09 E-02	4495
Sub-Total		2.17 E+00	899079

Bond Wires			
Item	% of Wire	Weight (g)	PPM
Au	99.99	6.01 E-02	24868

Chip			
Item	% of Chip	Weight (g)	PPM
Si	100	1.11 E-04	46

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Ag Filler	78	4.19 E-02	17331
Resin	22	1.18 E-02	4888
Sub-Total		5.37 E-02	22220

Package Totals	
Weight (g)	PPM
2.42 E+00	1000000

Molding Compound		
Item	PPM	Method
Pb	<2.0	EPA method #3052 (ICPAES)
Cd	<2.0	BS EN 1122:2001B (ICPAES)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)
PBB	<5.0	B3/264/EEC (GC/ECMS)
PBDE	<5.0	B3/264/EEC (GC/ECMS)

Die Attach Paste		
Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	ICP-AES
PBB	<5.0	USEPA3540 or 3550 (GC/MS)
PBDE	<5.0	USEPA3540 or 3550 (GC/MS)

Substrate		
Item	PPM	Method
Pb	<2	SGS Test Report
Cd	<2	SGS Test Report
Hg	<2	SGS Test Report
Cr+6	6.0	SGS Test Report
PBB	NA	NA
PBDE	NA	NA

STS-BC-G

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary

11/27/2005

